


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

|                             |  |                                      |
|-----------------------------|--|--------------------------------------|
| <b>1.1 Company</b>          |                           | STMicroelectronics International N.V |
| <b>1.2 PCN No.</b>          | MDG/18/10995   |                                      |
| <b>1.3 Title of PCN</b>     | ST Calamba Philippines additional assembly plant for STM8S/L & STM32 products in UFQFPN 5x5 & 7x7 packages |                                      |
| <b>1.4 Product Category</b> | STM8S/L & STM32 products in 5x5 & 7x7 packages   |                                      |
| <b>1.5 Issue date</b>       | 2018-08-05   |                                      |

**2. PCN Team**

|                                  |                            |
|----------------------------------|----------------------------|
| <b>2.1 Contact supplier</b>      |                            |
| <b>2.1.1 Name</b>                | MARSHALL DAVE              |
| <b>2.1.2 Phone</b>               |                            |
| <b>2.1.3 Email</b>               | dave.marshall@st.com       |
| <b>2.2 Change responsibility</b> |                            |
| <b>2.2.1 Product Manager</b>     | Ricardo Antonio DE SA EARP |
| <b>2.1.2 Marketing Manager</b>   | Veronique BARLATIER        |
| <b>2.1.3 Quality Manager</b>     | Pascal NARCHE              |

**3. Change**

|                     |   |                                   |
|---------------------|---|-----------------------------------|
| <b>3.1 Category</b> | <b>3.2 Type of change</b>   | <b>3.3 Manufacturing Location</b> |
| Materials           | Any change on substrate (part number, supplier, plant, design or composition of any layer, etc..) | ST Calamba Philippines            |

**4. Description of change**

|  |  |   |
|--|--|---|
|  | <b>Old</b>   | <b>New</b>  |
| <b>4.1 Description</b>   | Assembly site :<br>- Stats ChipPAC Jiangyin China (JSCC)   | Assembly site :<br>- Stats ChipPAC Jiangyin China (JSCC)<br>- ST Calamba Philippines - added<br>Bill Of Materilas (BOM) changes are described in 10995_ Additional information attached document. |
| <b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b> | Lead color and surface finish change depending on lead finishing. Package darkness changes depending on molding. |   |

**5. Reason / motivation for change**

|                             |  |
|-----------------------------|--|
| <b>5.1 Motivation</b>       | ST Microcontrollers Division decided to qualify an additional source to maintain best in class service level to our customers, improving flexibility on manufacturing sites. |
| <b>5.2 Customer Benefit</b> | CAPACITY INCREASE  |

**6. Marking of parts / traceability of change**

|                        |  |
|------------------------|--|
| <b>6.1 Description</b> | Change is visible through assembly traceability plant, in the marking:<br>- "GQ" for Stats ChipPAC Jiangyin China (JSCC)<br>- "78" for ST Calamba Philippines<br>Please refer to PCN 10995 – Additional information attached document. |
|------------------------|--|

**7. Timing / schedule**

|  |              |
|--|--------------|
| <b>7.1 Date of qualification results</b>   | 2018-09-06   |
| <b>7.2 Intended start of delivery</b>      | 2018-10-27   |
| <b>7.3 Qualification sample available?</b> | Upon Request |

**8. Qualification / Validation**

|                        |  |
|------------------------|--|
| <b>8.1 Description</b> | 10995 RERMCD1812 - ST CALAMBA additional source UFQFPN 5x5 7x7 packages PCN10995 Plan - 25 July 18.pdf |
|------------------------|--|

|  |                            |            |            |
|--|----------------------------|------------|------------|
| 8.2 Qualification report and qualification results | Available (see attachment) | Issue Date | 2018-08-05 |
|--|----------------------------|------------|------------|

**9. Attachments (additional documentations)**

10995 Public product.pdf  
10995 RERMCD1812 - ST CALAMBA additional source UFQFPN 5x5 7x7 packages PCN10995 Plan - 25 July 18.pdf  
10995 PCN10995\_Additional information.pdf

**10. Affected parts**

| 10. 1 Current           |                         | 10.2 New (if applicable) |
|-------------------------|-------------------------|--------------------------|
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | STM32F042C6U6           |                          |
|                         | STM32F413CGU6           |                          |
|                         | STM32L031C6U3           |                          |
|                         | STM32L031C6U6           |                          |
|                         | STM32L072KBU3           |                          |
|                         | STM32L431KBU3           |                          |
|                         | STM32L431KCU6           |                          |
|                         | STM32L432KCU3           |                          |
|                         | STM32L433CBU6           |                          |
|                         | STM32L433CCU3           |                          |
|                         | STM32L451CCU3           |                          |
|                         | STM32L451CCU6           |                          |
|                         | STM32L452CCU6           |                          |
|                         | STM32L452CEU3           |                          |
|                         | STM32L452CEU6           |                          |

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